



SOT97-1

plastic dual in-line package; 8 leads (300 mil)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP8
Package type industry code	DIP8
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	050G01
JEDEC package outline code	MO-001
JEITA package outline code	SC-504-8
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

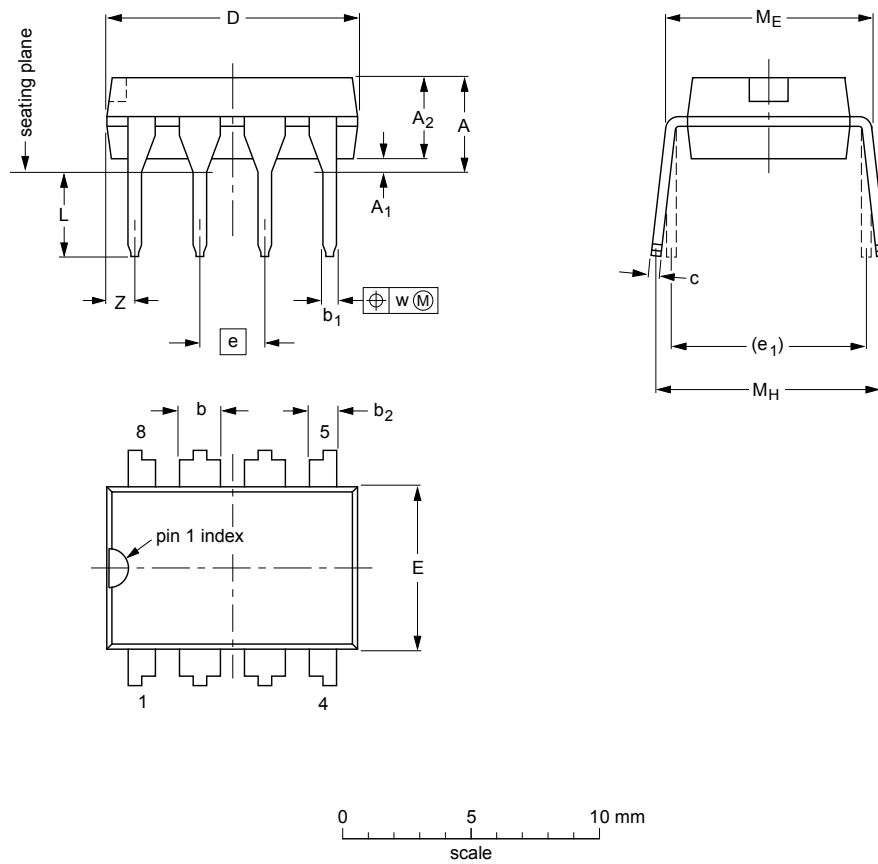
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.2	-	9.5	9.8	mm
E	package width	6.2	-	6.34	6.48	mm
A	seated height	[tbd]	-	[tbd]	4.2	mm
A ₂	package height	[tbd]	-	[tbd]	3.2	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

DIP8: plastic dual in-line package; 8 leads (300 mil)

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.14	0.53 0.38	1.07 0.89	0.36 0.23	9.8 9.2	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	1.15
inches	0.17	0.02	0.13	0.068 0.045	0.021 0.015	0.042 0.035	0.014 0.009	0.39 0.36	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.045

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT97-1	050G01	MO-001	SC-504-8			99-12-27 03-02-13

Fig. 1. Package outline DIP8 (SOT97-1)

3. Legal information

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Date of release: 8 February 2016
